What is claimed is:

1. A semiconductor laser module comprising:

a semiconductor substrate;

a laser diode secured on said substrate for emission of a forward laser beam from a forward end thereof and for emission of a backward laser beam from a point source on a rearward end thereof in a horizontal direction; and

a photodiode secured on said substrate, said photodiode having a light receiving surface extending in the horizontal direction by length L from an edge proximate to the laser diode for receiving a lower half of said backward laser beam, said light receiving surface being lower than said point source by a vertical distance Y, said edge being spaced a horizontal distance Z from said point source of the laser diode,

wherein the horizontal distance Z is equal to or greater than $(Y/\tan\theta) - L$, where θ is a vertical angle in which said lower half of the backward laser beam radiates from said point source.

2. The semiconductor laser module of claim 1, wherein said laser diode and said photodiode are not covered with resin.

3. The semiconductor laser module of claim 1, wherein said substrate has an upper surface and a lower surface, and wherein said laser diode is secured on said upper surface and said photodiode is secured on said lower surface.

4. The semiconductor laser module of claim 2, wherein said lower surface and said light receiving surface are parallel to each other.

5. The semiconductor laser module of claim 1, wherein said semiconductor substrate is formed of silicon.

6. The semiconductor laser module of claim 1, wherein said substrate is formed of a single-crystalline silicon and said lower surface is an anisotropically etched surface.

7. The semiconductor laser module of claim 1, further comprising a laser driver for driving the laser diode with a high frequency electrical signal.

8. The semiconductor laser module of claim 7, wherein said laser driver is secured on said lower surface in a position adjacent to said photodiode and remote from said laser diode.

9. The semiconductor laser module of claim 8, wherein said substrate is formed with a recess in which said lower surface is created and said photodiode and said laser driver are secured, further comprising:

an electrode patterned on said upper surface extending from said laser diode to a position close to said laser diode; and

a bonding wire for connecting said laser diode to one end of said electrode, whereby said high frequency electrical signal is supplied through said bonding wire and said electrode to said laser diode.